

ABSTRACT

The present disclosure provides a semiconductor process device, and belongs to the field of semiconductor equipment. The semiconductor process device includes:
5 a process pipe, a plurality of gas intake pipes, and a plurality of groups of electrode assemblies, a process chamber and a plurality of buffer chambers are formed inside the process pipe, the plurality of gas intake pipes correspondingly extend into the plurality of buffer chambers, an exhaust port communicated with the process chamber is provided at a sidewall of the process pipe, each of the buffer chambers is arranged
10 corresponding to at least one group of electrode assemblies, and the electrode assemblies extend into the buffer chambers, and are connected to a radio frequency power supply; the electrode assembly includes a deformable electrode core, a plurality of electrode tubes, and an electrode mesh, the plurality of electrode tubes are sequentially arranged along an extension direction of the electrode core, a preset gap
15 is provided between every two adjacent electrode tubes, and the electrode core is inserted into the plurality of electrode tubes, and is respectively connected to the plurality of electrode tubes; and the electrode mesh is disposed along the extension direction of the electrode core, and is nested outside the plurality of electrode tubes. The present disclosure can solve the problems of electrode of high cost and short
20 service life.